


Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Materials:

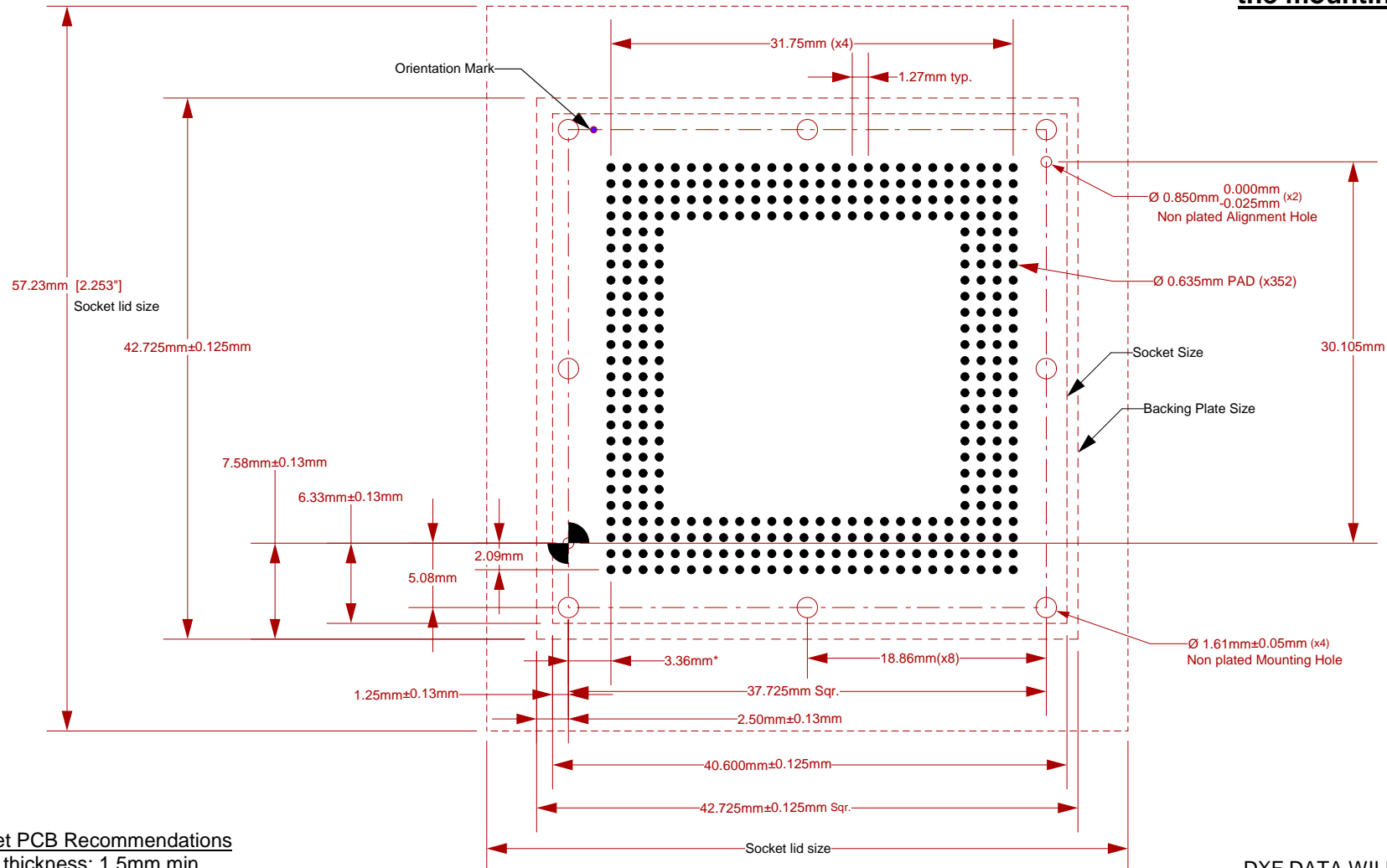
- △1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- △2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- △3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- △4 Compression Screw: Black anodized Aluminum. Height = 27 mm, Fluted Knob
- △5 Pogo Pin:
Plungers - Hardened Steel/ Gold plated
Barrel - Copper Alloy/ Gold plated
Spring - Stainless Steel/ Gold wire
- △6 Pogo Pin Guides: Ceramic filled peek or Torton
- △7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 3/8" long.
- △8 Backing Plate: Black anodized Aluminum
- △9 Insulation Plate: FR4/G10
- △10 Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- △11 Latch: Black anodized Aluminum.

	SS-BGA352A-01 Drawing	Status: Released	Scale: N/A	Rev: A
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 2/13/08	
		File: SS-BGA352A-01 Dwg	Modified:	

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Target PCB Recommendations

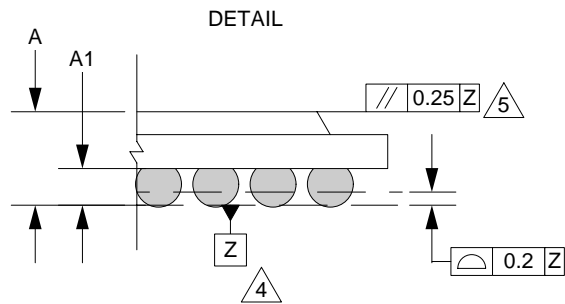
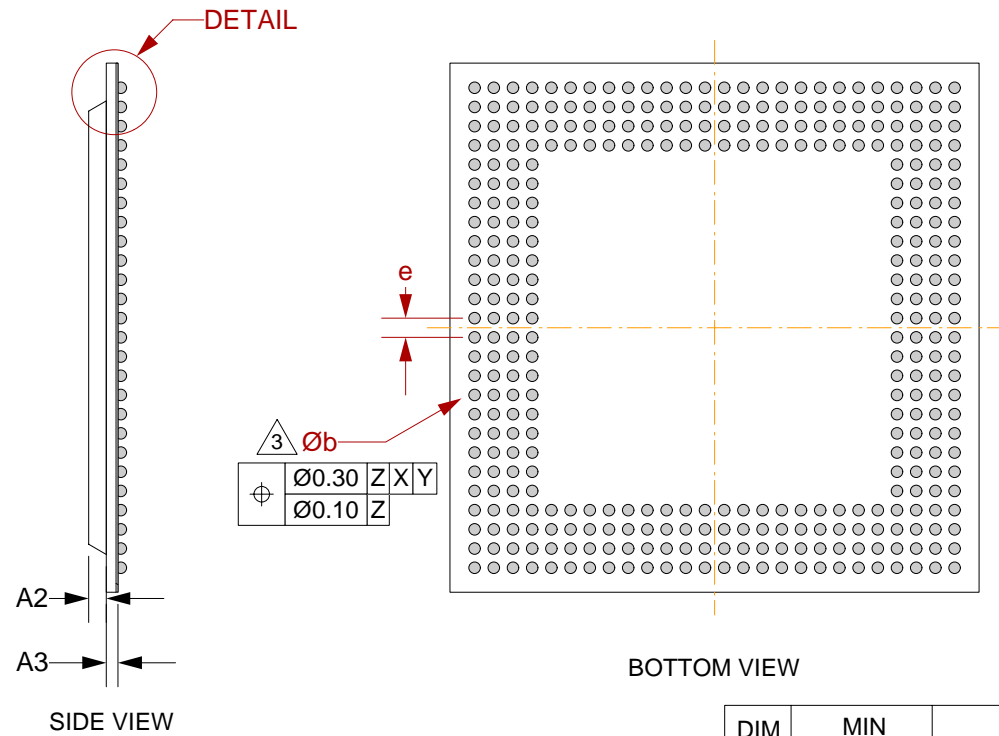
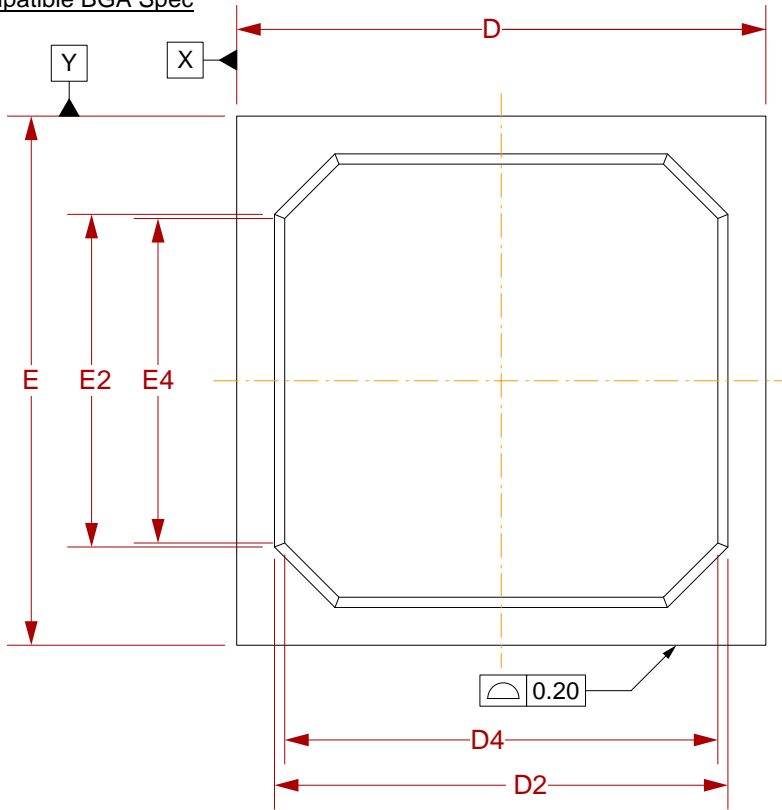
Total thickness: 1.5mm min.
Plating: Gold or Solder finish



DXF DATA WILL BE PROVIDED

	SS-BGA352A-01 Drawing	Status: Released	Scale: 2:1	Rev: A
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		File: SS-BGA352A-01 Dwg	Modified:	

Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.



1. Dimensions are in millimeters.

2. Interpret dimensions and tolerances per ASME Y14.5M-1994.


3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.

4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

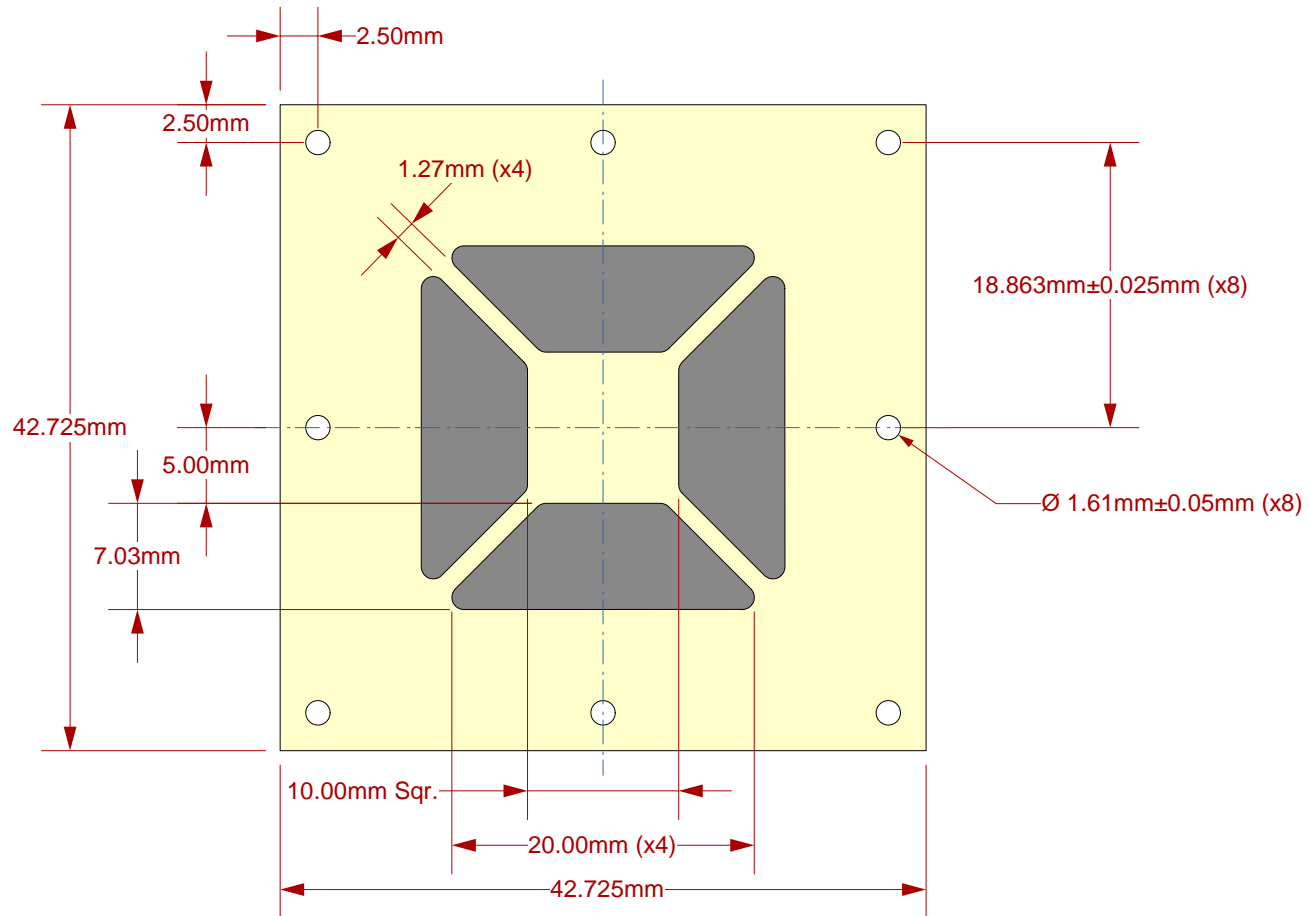
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A	2.13	2.53
A1	0.5	0.7
A2	1.12	1.22
A3	0.56 REF	
b	0.6	0.8
D	35.0 BSC	
D2	30.0	
D4	22.0	
E	35.0 BSC	
E2	30.0	
E4	22.0	
e	1.27 BSC	

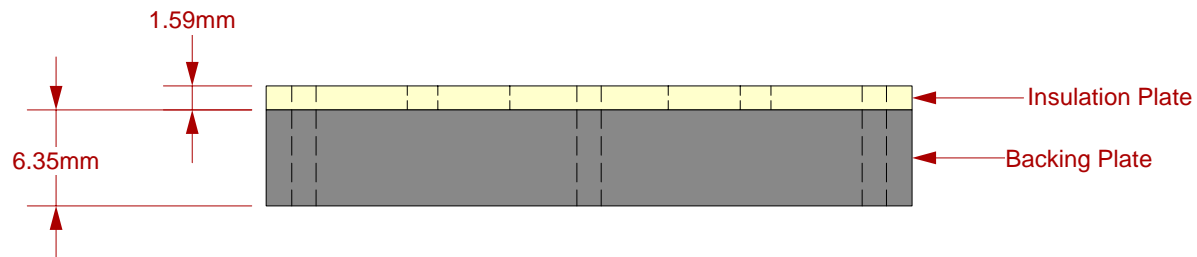
Array 26x26

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	<p>Drawing: J. Glab</p>	<p>Date: 2/13/08</p>		
	<p>File: SS-BGA352A-01 Dwg</p>	<p>Modified:</p>		

Top View




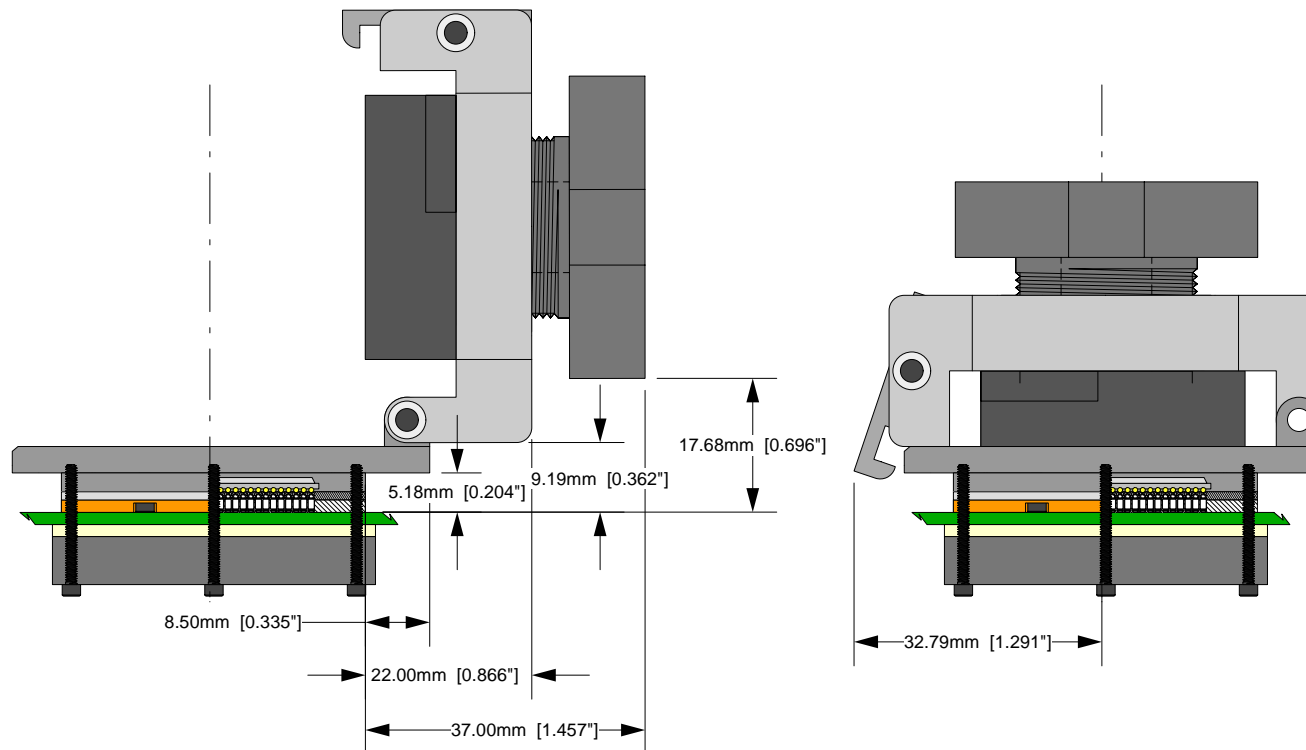
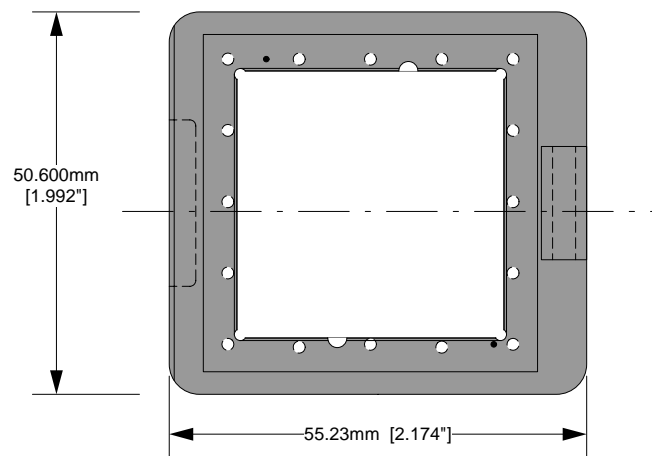
Side View




Description: Insulation Plate and Backing Plate

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)

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 (Unless stated otherwise)